

SUPPORT & RESIN REMOVAL

The PostProcess™ DEMI 200™ leverages our proprietary patented Submersed Vortex Cavitation technology for revolutionary post-printing efficiencies; combining software, hardware, and chemistry features for optimal resin and support removal.

- Vortex pumping scheme ensures uniform chemistry exposure to finishes parts with unprecedented consistency.
- Precision control over temperature and ultrasonic-generated cavitations for accelerated process times.
- Variable energy output to adapt to material and geometry needs results in reduced damage.



SOFTWARE FEATURES

- Variable temperature: 70-156°F / 21-69°C
- Programmable cycle time
- Proprietary Agitation Algorithms

HARDWARE FEATURES

- Digital interface
- Piezo-electric Ultrasonics
- Stainless steel envelope
- Removable envelope lid
- Magnetically driven pump

ELECTRICAL

- Voltage: 110V/240V, 60/50Hz
- Amperage: 8.5A/3.9A
- Connector: NEMA 5-15P

SAFETY FEATURES

- Auto power down
- Noise reducing features for a low dBa

MATERIALS AND TECHNOLOGIES



SLA



DLP



CLIP



FDM



POLYJET

Resin Removal

Support Removal

SIZE

Envelope: 18" L x 10" W x 6" H
46 cm x 25 cm x 15 cm

Footprint: 23.5" L x 18" W x 15.5" H
60 cm x 46 cm x 39 cm

Weight: 35 lbs. / 15 kg empty; 75 lbs. / 34 kg full

CONSUMABLES

Capacity: 5 Gallons / 19 Liters

Detergent: PLM-101-SUB for Polyjet
PLM-201-SUB for FDM
PLM-403-SUB for SLA, CLIP, DLP